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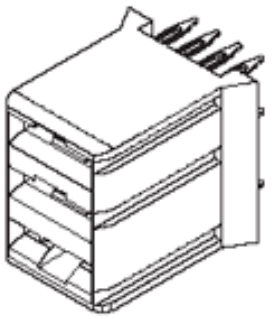
Part Number: 0736565001
Status: Active
Overview: hdm
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm (30µ")



Series image - Reference only

Documents:
Drawing (PDF)
RoHS Certificate of Compliance (PDF)
Product Specification PS-73670-9999 (PDF)

General

Product Family	Backplane Connectors
Series	73656
Application	Backplane
Comments	Backplane Power Module
Component Type	Power Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.093 In
PCB Thickness Recommended (mm)	2.36 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	35.2
Plating min: Termination (µm)	0.88
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

EU RoHS
RoHS Compliant by Exemption
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

50
Pb

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
73656Series

Mates With
73651 HDM® Board-to-Board Daughterboard Power Module

Electrical

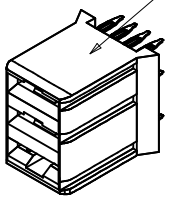
Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	500V AC

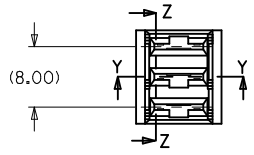
Material Info

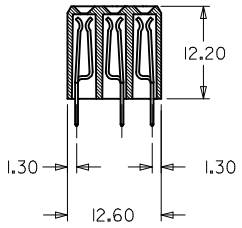
Reference - Drawing Numbers

Application Specification	AS-73656-1998
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

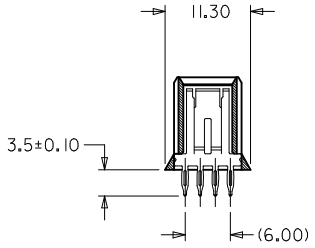
ASSEMBLY NUMBER	FINISH
73656-0000	SEE NOTE 2.
73656-0001	SEE NOTE 3.



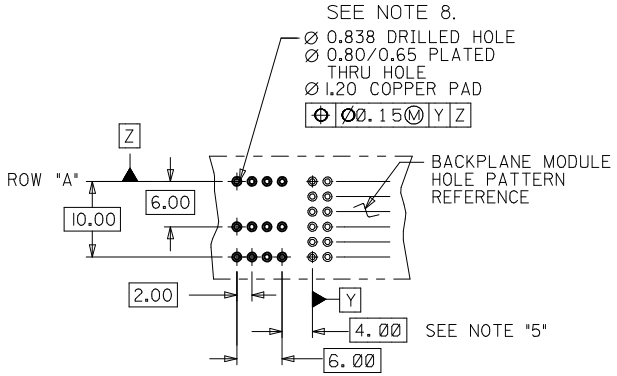




SECTION: Z-Z
ROTATED 90° CW



SECTION: Y-Y



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
   TERMINAL - COPPER ALLOY
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.76 micrometer MINIMUM THICKNESS: NICKEL (Ni)AND GOLD FLASH OVERALL
3. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.76 micrometer MINIMUM THICKNESS: TIN/LEAD (Sn/Pb)OVER NICKEL (Ni) IN COMPLIANT AREA: NICKEL (Ni) OVERALL ON REMAINING WITH SELECTIVE GOLD (Au) FLASH.
4. THIS DIMENSION MUST BE A MULTIPLE OF 4.00 mm.
5. DIMENSIONS ARE IN MILLIMETERS.
6. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
7. PACKAGE ASSEMBLIES PER PK-70873-0819.
8. HOLE SIZE SPECIFICATION IS FOR TIN/LEAD PLATED HOLES ONLY. FOR OTHER PLATING TYPES SEE MOLEX APPLICATION AS-73670-9996.
9. THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS B.

ADD NOTES 8 & 9 — EC NO: UCP2009-1813 — DRWN:SDANNELLEY 2009/07/17 — CH'KD:BSMART 2009/07/24 — APPR:SMILLER 2009/07/24 — DESCRIPTION — REV H

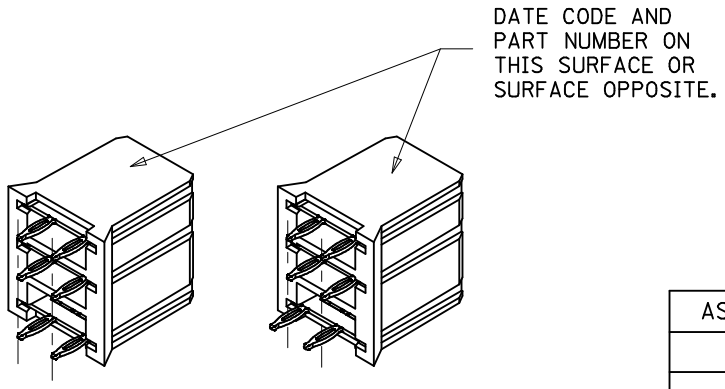
QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

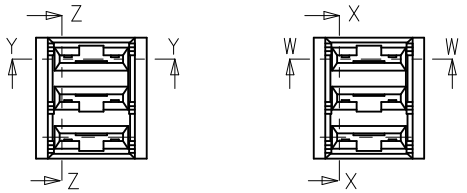
DIMENSION STYLE	MM ONLY
SCALE	1:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	ELO 1998/05/21
CHECKED BY / DATE	SMR 1998/05/21
APPROVED BY / DATE	CAB 1998/05/21
TITLE	SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)
	MOLEX INCORPORATED
MATERIAL NO.	SEE TABLE
DOCUMENT NO.	SDA-73656-*00*
SHEET NO.	1 OF 4
SIZE	C

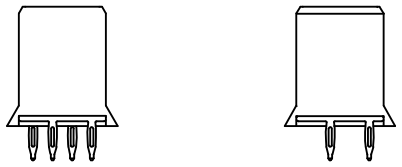


73656-100* 73656-200*

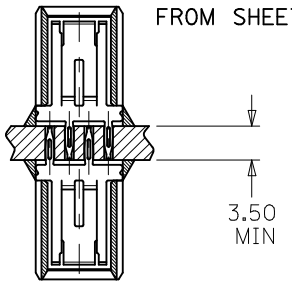
MIDPLANE OPTION

ASSEMBLY NUMBER	FINISH (SEE SHT 1)
73656-1000	SEE NOTE 2. (GOLD TAILS)
73656-2000	
73656-1001	SEE NOTE 3. (TIN/LEAD TAILS)
73656-2001	

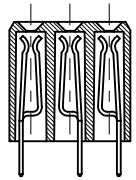




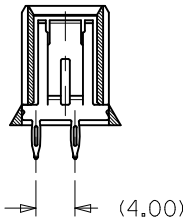
73656-200* 73656-100*



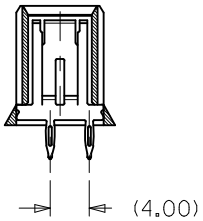
BACK-TO-BACK
MOUNTING APPLICATION



SECTION X-X
SECTION Z-Z
ROTATED 90° CW



SECTION: Y-Y

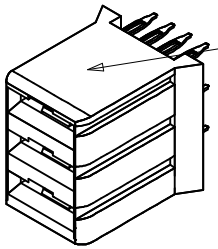


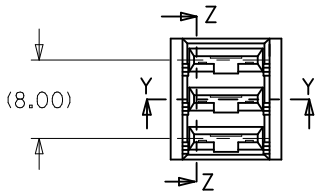
SECTION: W-W

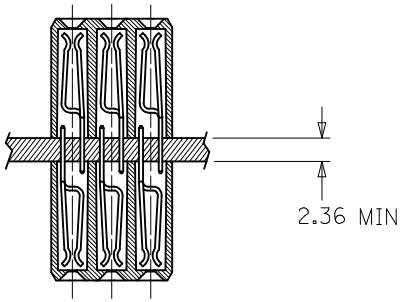
SEE SHEET 1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
EC NO: UCP2009-1813 2009/07/17	▼=0	mm / INCH
DRWN:SDANNELLEY 2009/07/24	Ⓒ=0	4 PLACES ± --- / ± ---
CHKD:BSMART 2009/07/24		3 PLACES ± --- / ± ---
APPR:SMILLER 2009/07/24		2 PLACES ± --- / ± ---
DESCRIPTION		1 PLACE ± --- / ± ---
REV		ANGULAR ±1/2°
H		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

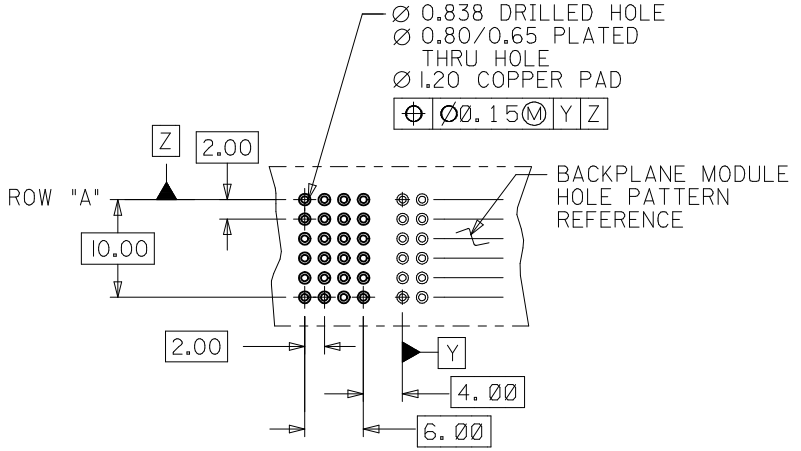
DIMENSION STYLE: MM ONLY	SCALE: 1:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: ELO — DATE: 1998/05/21	TITLE: SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)		
CHECKED BY: SMR — DATE: 1998/05/21			
APPROVED BY: CAB — DATE: 1998/05/21	molex MOLEX INCORPORATED		
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SDA-73656-*00*	SHEET NO.: 2 OF 4	
SIZE: B			

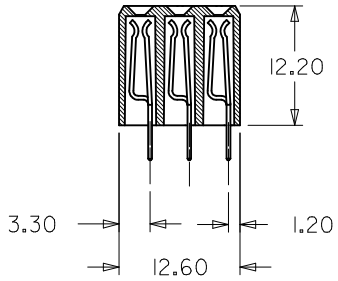
ASSEMBLY NUMBER	FINISH (SHT 1)
73656-5000	SEE NOTE 2.
73656-5001	SEE NOTE 3.



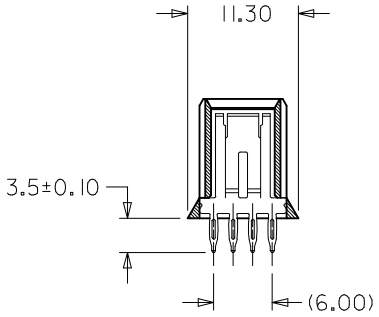








SECTION: Z-Z
ROTATED 90° CW



SECTION: Y-Y

SEE SHEET 1
EC NO: UCP2009-1813 2009/07/17
DRWN:SDANNELLEY 2009/07/24
CH'KD:BSMART
APPR:SMILLER 2009/07/24
DESCRIPTION
H
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 1:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

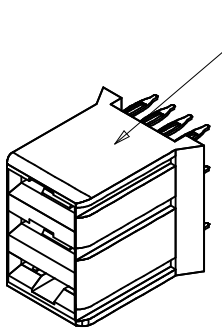
	DRAWN BY	DATE
	ELO	1998/05/21
	CHECKED BY	DATE
	SMR	1998/05/21
	APPROVED BY	DATE
	CAB	1998/05/21

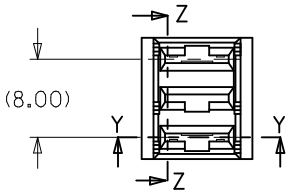
TITLE: SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)

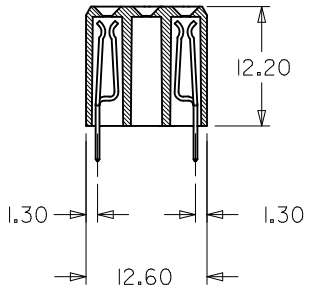
MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SDA-73656-*00*
SHEET NO.: 3 OF 4
SIZE: B

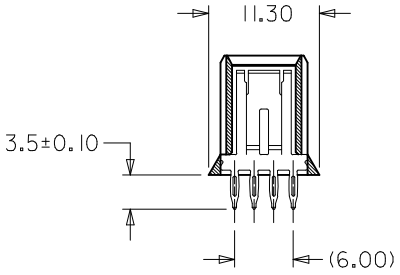
ASSEMBLY NUMBER	FINISH
73656-0180	SEE NOTE 2.
73656-0181	SEE NOTE 3.



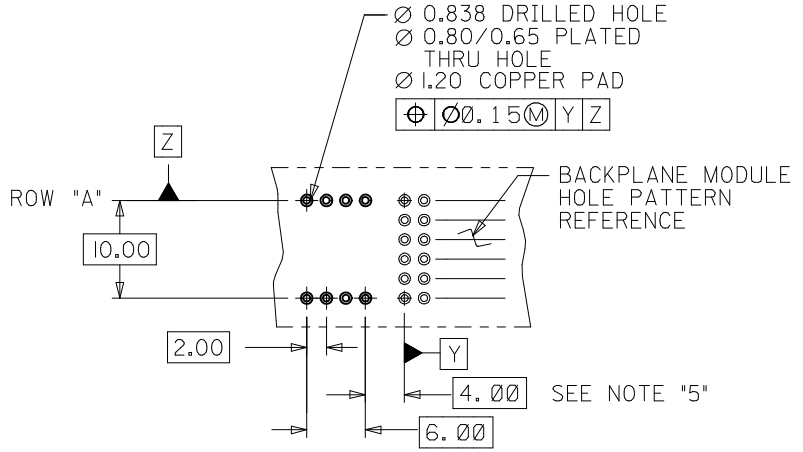




SECTION: Z-Z
ROTATED 90° CW



SECTION: Y-Y



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

SEE SHEET 1
EC NO: UCP2009-1813
DRWN:SDANNELLEY 2009/07/17
CHKD:BSMART 2009/07/24
APPR:SMILLER 2009/07/24
DESCRIPTION
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 1:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

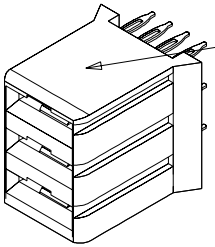
	DRAWN BY	DATE
	ELO	1998/05/21
	CHECKED BY	DATE
	SMR	1998/05/21
	APPROVED BY	DATE
	CAB	1998/05/21

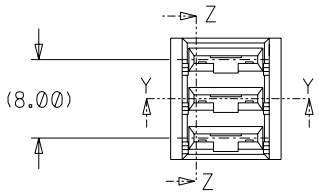
TITLE: SALES ASSY , HDM BACKPLANE POWER MODULE (PRESSFIT)

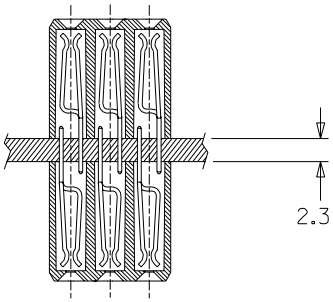
MOLEX INCORPORATED

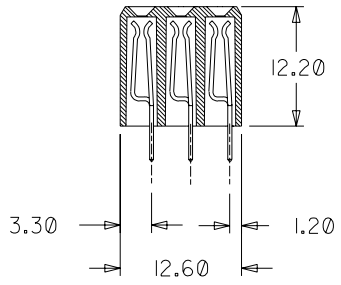
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SDA-73656-*00*
SHEET NO.: 4 OF 4
SIZE: B

ASSEMBLY NUMBER	FINISH (SHT 1)
73656-5000	SEE NOTE 2.
73656-5001	SEE NOTE 3.

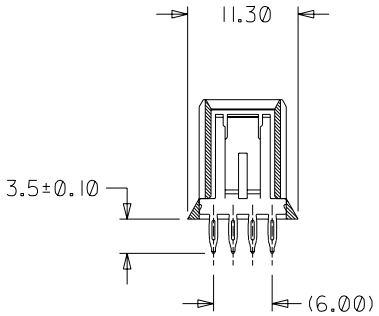




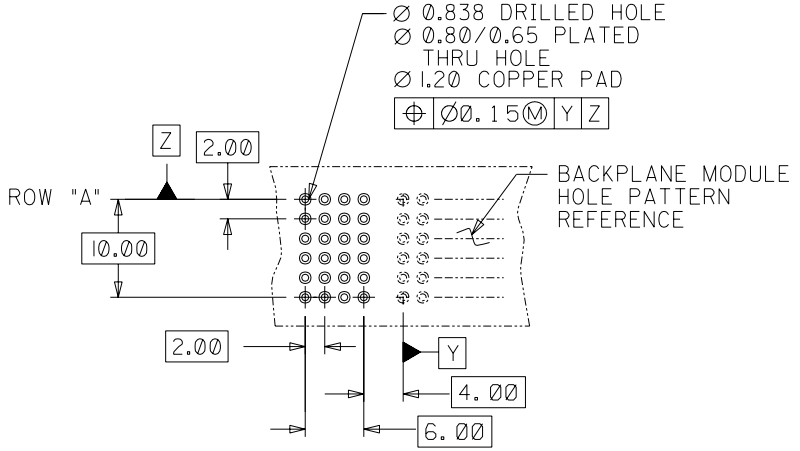




SECTION: Z-Z
ROTATED 90° CW



SECTION: Y-Y



LTR.	REVISIONS	LTR.	REVISIONS
		B	SEE SHEET 1
G	SEE SHEET 1	A1	SEE SHEET 1
E	SEE SHEET 1	A	SEE SHEET 1

DIMENSIONS SHOWN (METRIC) INCH

UNLESS OTHERWISE SPECIFIED
TOLERANCES: ANGULAR ± 1/2°

	INCH	METRIC
3 PLACE	± N/A	---
2 PLACE	± N/A	± ---
1 PLACE	---	± ---

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DRWG. BY	ELO	CHK'D. BY	SMR
APP'D BY	BIXLER	SCALE	2 : 1

[redacted] REVISE ONLY ON CAD SYSTEM

TITLE: SALES ASSY, HDM BACKPLANE POWER MODULE (PRESS FIT)

MOLEX INCORPORATED
LISLE,ILL. 60532 U.S.A.

SHEET NO. 3

DATE 98/05/21

PART NO. SEE CHART

DRWG. NO. SDA-73656-*00*

FILE NAME S73656X3 DGN

DIV. DA

SIZE B

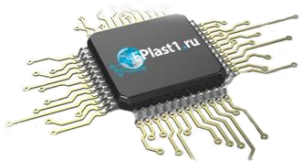
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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